

Package Qualification Report

Package : 64LQFP (Lead Free, SESS)

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Qualification Chip Description

- ✓ **Device Name : S5L9XXXXXX**
- ✓ **Process : L35**
- ✓ **Chip Size : 5260 x 5556 (um²)**
- ✓ **Adhesive : Ag-Epoxy**
- ✓ **Wire : 1.0 mil Pd Alloy**
- ✓ **EMC : Low Stress Only**
- ✓ **Tin Plating(Lead Free) : Sn/Bi (Bi Contents: 1~4%)**
- ✓ **Package Body Size: 10 x 10 (mm²)**
- ✓ **PKG Thickness : 1.4 (mm)**

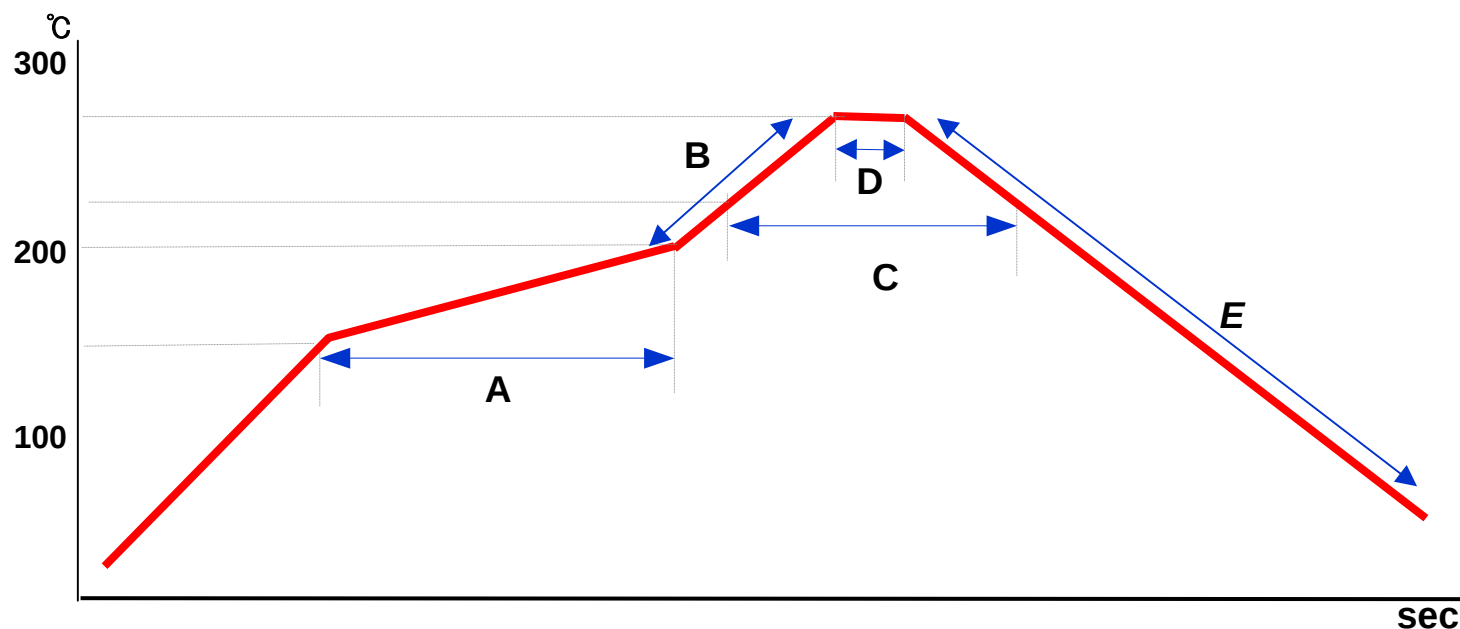
Qualification Results

Reliability Test Results

Items	Test Condition	Test Time	Sample Size	Results
Pre-Conditioning	30°C, 60%R.H. IR 3 times (Peak Temp.260+0°C)	192Hrs	153	0/153
TC	-65°C<-> 150°C	500CIs	45	0/45
PCT	121°C, 100%R.H. 2atm	168Hrs	45	0/45
HTS	150°C	500Hrs	45	0/45

❖ 64-LQFP-1010(SESS)는 당사의 Package Qualification 규정을 만족하였습니다.

IR Reflow Profile & Moisture Absorption Condition for Lead-Free Package



Items	Preheat(A)	Ramp-Up Rate(B)	Maintain(C)	Reflow Peak(D)	Ramp-Down Rate(E)
Condition	150~200℃ 60~180sec	3℃/sec max.	Above 217℃ 60~150sec	260+0℃ *20~40sec	6℃/sec max.

• Peak Temp. Tolerance : +0℃/-5℃ (Based on Machine Variation Capability)

* Time within 5℃ of Actual Peak Temp.